



# A 190-210GHz Power Amplifier with 17.7-18.5dBm Output Power and 6.9-8.5% PAE

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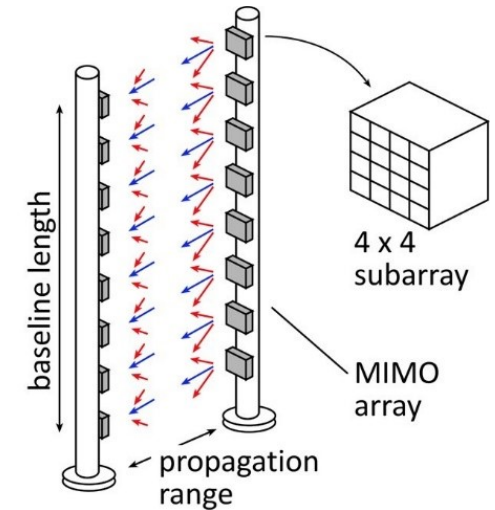


# Outline

- Motivation for mm-wave frequencies and prior work.
- Application for the amplifier.
- Amplifier design
  - Power and driver cells
  - Low-loss compact combiner
- Measurement results
- Summary and conclusion

# mm-wave Communication (140-1000 GHz)

- Objective
  - Support high data rate communication.
  - Spatial multiplexing for high capacity.
  - Cover long distance.
- Benefits (140- 1000 GHz)
  - Large available spectrum, high data rate.
  - Shorter  $\lambda$ : more channels for the same array size.
- Challenge
  - Atmospheric attenuation is high  $P_R \propto \frac{\lambda^2}{R^2} e^{-\alpha R}$ .





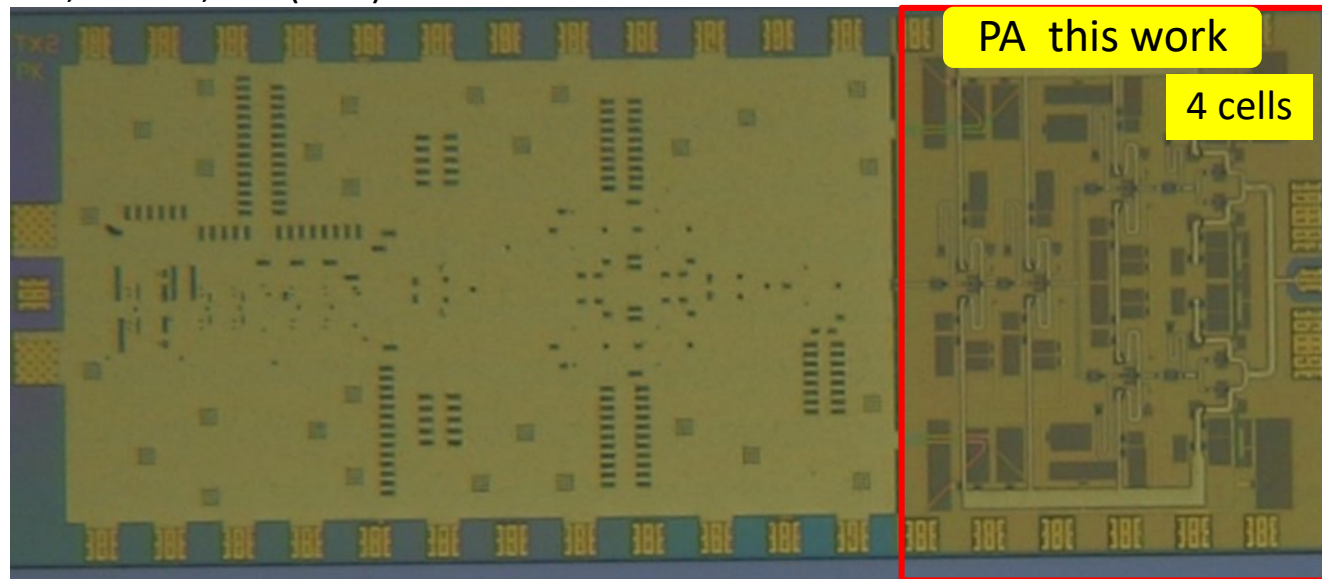
# Prior Work at G-band

- At 200GHz, CMOS shows 9.4dBm with only 1.03% PAE [2].
- SiGe shows 13.5dBm with ~2% drain efficiency [3]
- GaN demonstrates higher power with <2.4% peak PAE [4], [5].
- InP presented the highest power and efficiency [6]-[18].
- Key points
  - Designs are not optimized for the highest PAE at  $OP_{1dB}$ . PAE at  $OP_{1dB} < 3\%$
  - Power measurement accuracy at the linear region is challenging.

# This Work (190-210GHz)

- Optimize for the highest efficiency at  $OP_{1dB}$ .
- $OP_{1dB} \sim 17.4\text{dBm}$ , PAE: 6.4% at  $OP_{1dB}$ , Gain  $\sim 23\text{dB}$ .
- Accurate power measurement at the linear region.
- This amplifier is integrated to a 200GHz transmitter (not published).

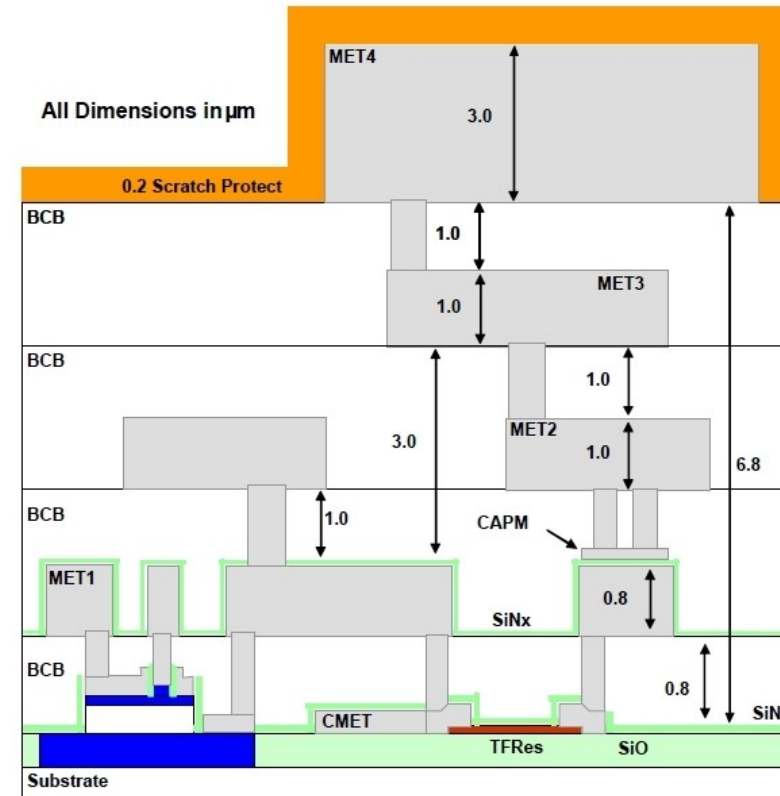
2,900 x 1,200 ( $\mu\text{m}^2$ )



200GHz transmitter, not published

# 250nm InP HBT Process (Teledyne [6])

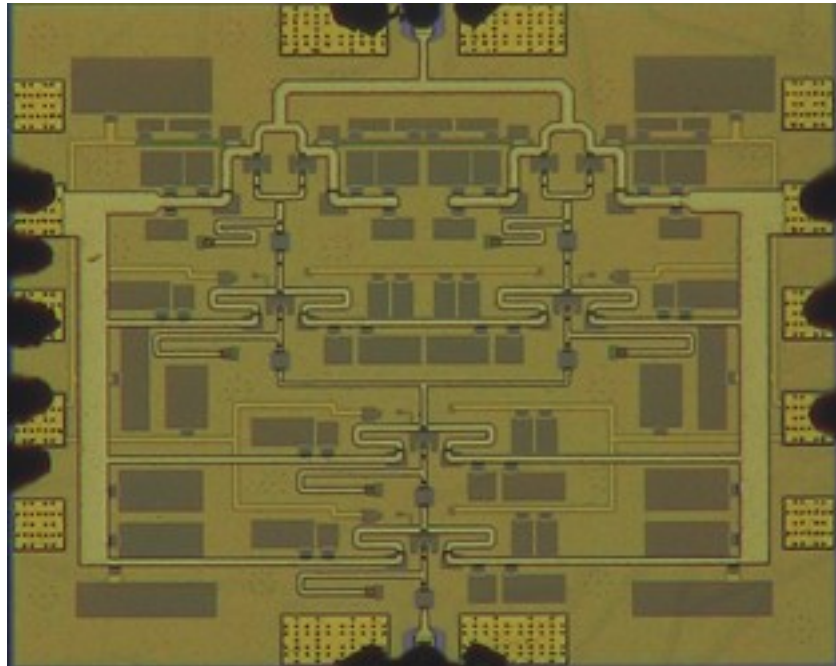
- Mm-wave amplifier requires fast technologies.
- $f_{\max} = 650\text{GHz}$ .
- $BV_{CE0} = 4.5\text{V}$ .
- $J_{\max} = 3\text{mA}/\mu\text{m}$ .
- Four Au interconnect.
- MIM cap ( $0.3\text{fF}/\mu\text{m}^2$ ).
- TFR ( $50\Omega/\text{square}$ ).



Cross section of TSC250 IC

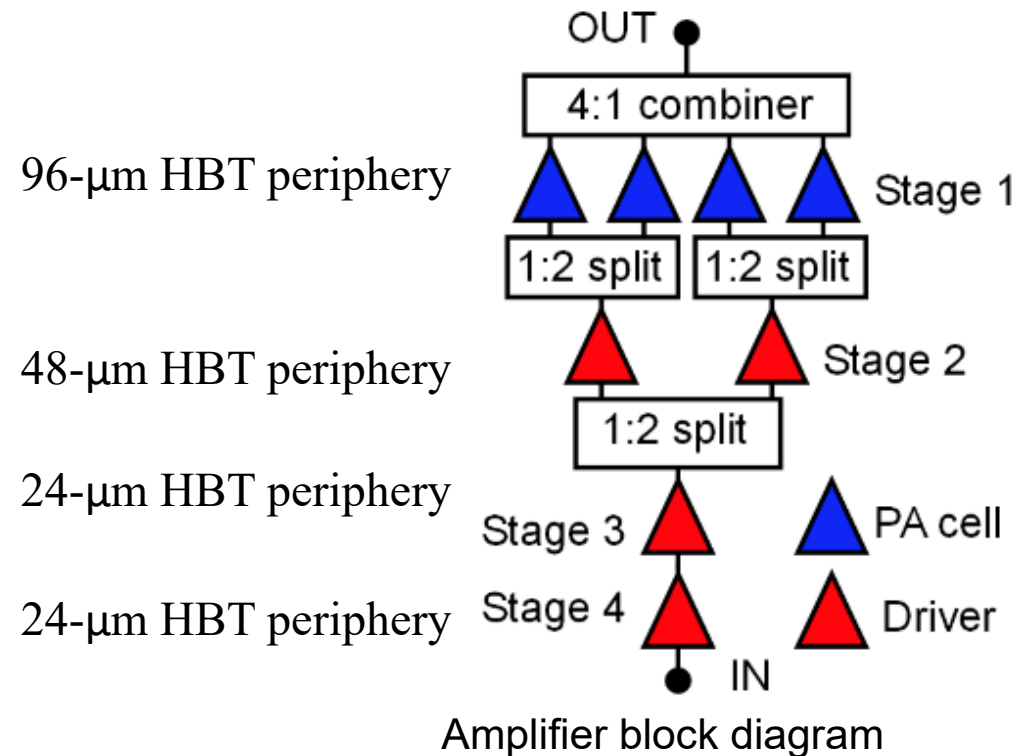
# Power Amplifier Design

- Four stages amplifier.
- Combine four power cells.
- Driver scaling sustains good PAE.



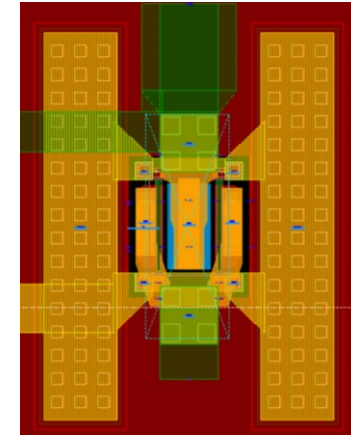
Amplifier micrograph

- Power combining techniques
  - Parallel combining: 4:1 transmission line combiner.
  - Series combiner: stacked unit cell.

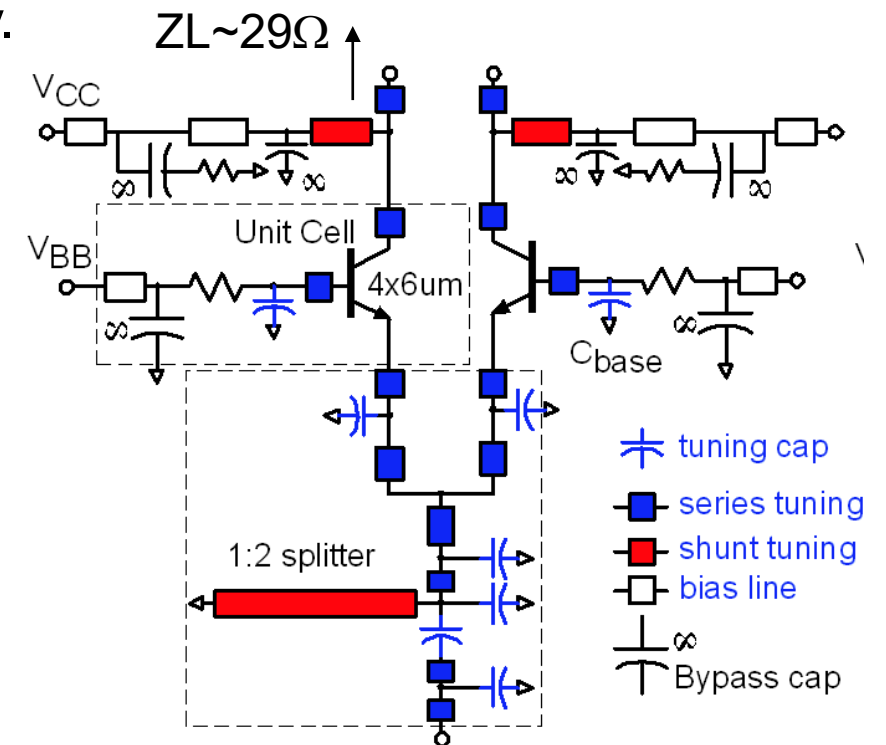


# Power Cell Design

- CB architecture with finite base impedance.
  - Superior PAE at  $OP_{1dB}$ , compared to CE or grounded CB, due to the feedback linearization [14].
- Base capacitances
  - Maximum value: limited by the self resonance frequency.
  - Minimum value: limited by the acceptable gain.
- Shunt transmission lines tunes the transistor parasitics.
- Each cell requires  $\sim 29\Omega$  load impedance.
- Matching considerations
  - Staggered tuning for better bandwidth.
  - Input impedances are close to the loadline of the driver to ensure proper saturation.



Transistor footprint with cap

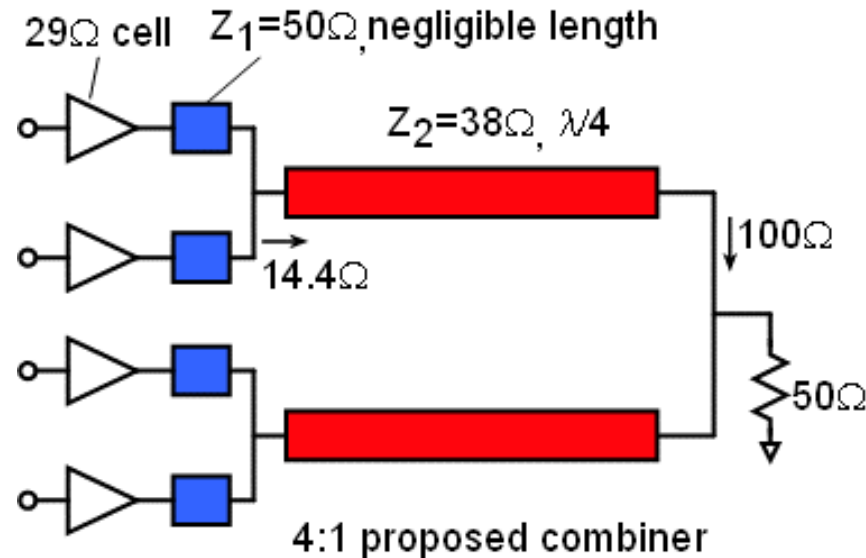


Power cell schematic



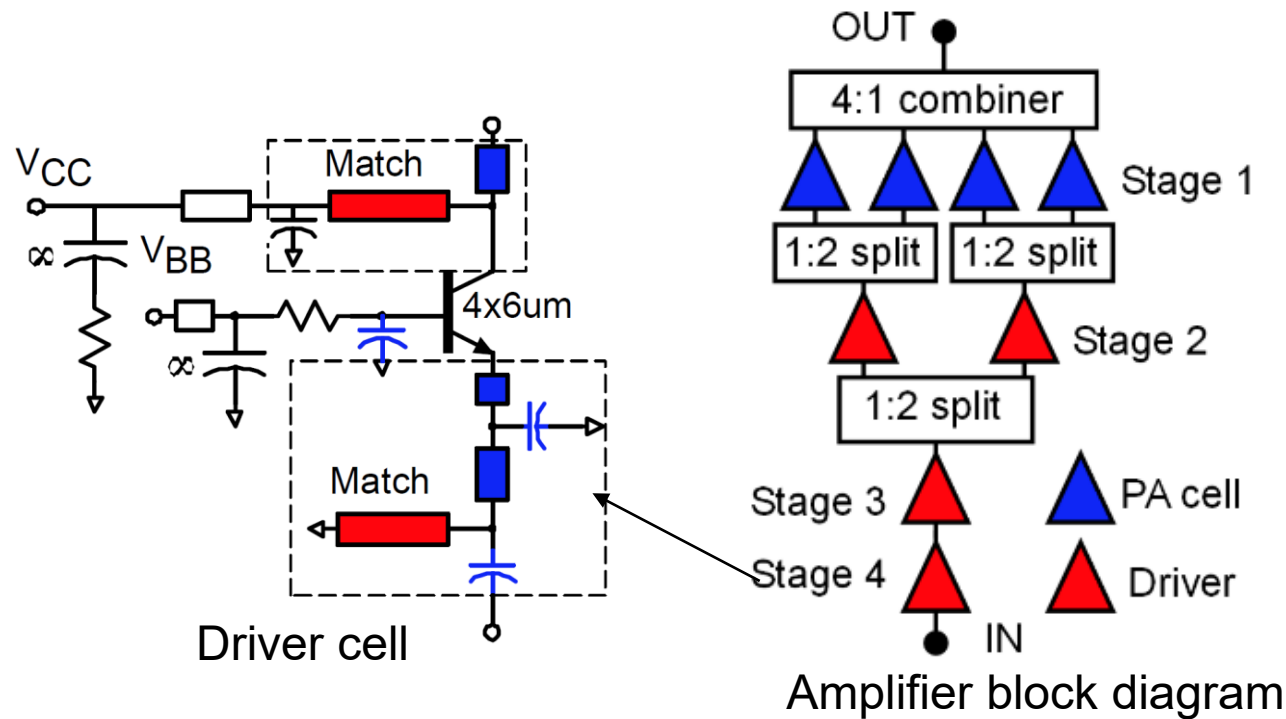
# Combiner Design

- Transmission line combiners have low loss and very compact [14], [15], [17].
- Low loss 4:1 transmission line combiner.
- Combiner transforms  $50\Omega$  to the required loadline impedance for each cell ( $\sim 29\Omega$ ) using a single  $\lambda/4$  transmission line.
- Each two cells are combined by a TL with negligible electrical length.
- The required impedance for the two combined cells is  $29/2\Omega$ .
- The quarter line's impedance is chosen to transform  $100\Omega$  to  $29/2\Omega$ .



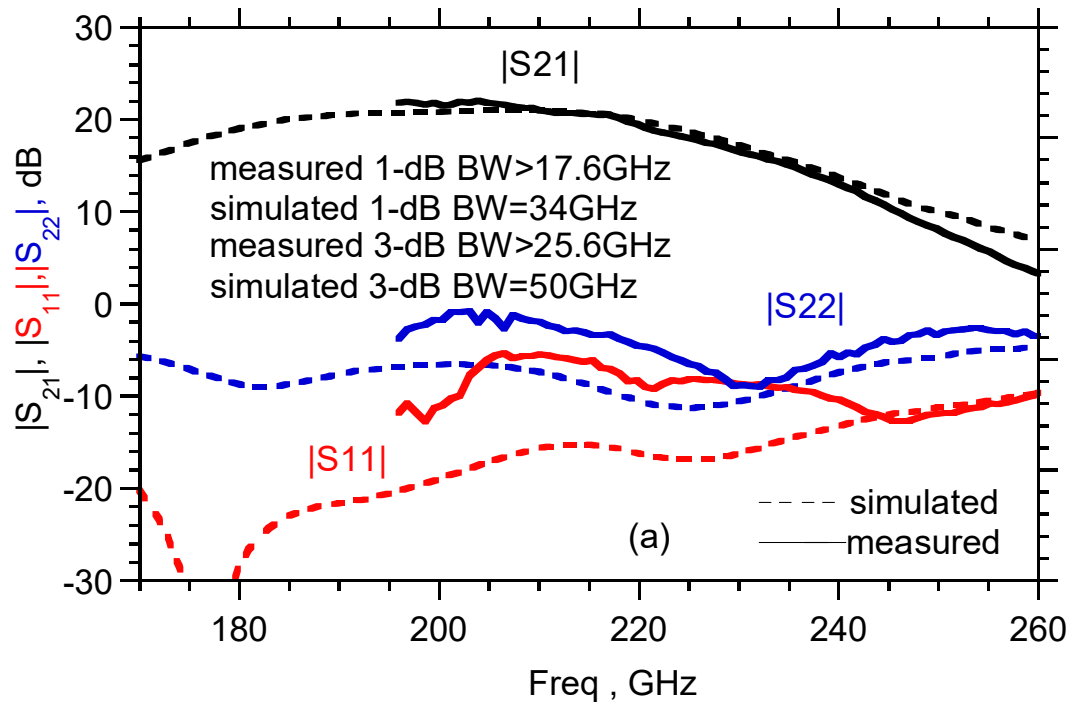
# Driver Cell Design

- Design is similar to the power cell.
- Architecture uses CB with finite base capacitance.
- Conservative driver scaling ensures hard compression characteristics at the expense of PAE degradation.

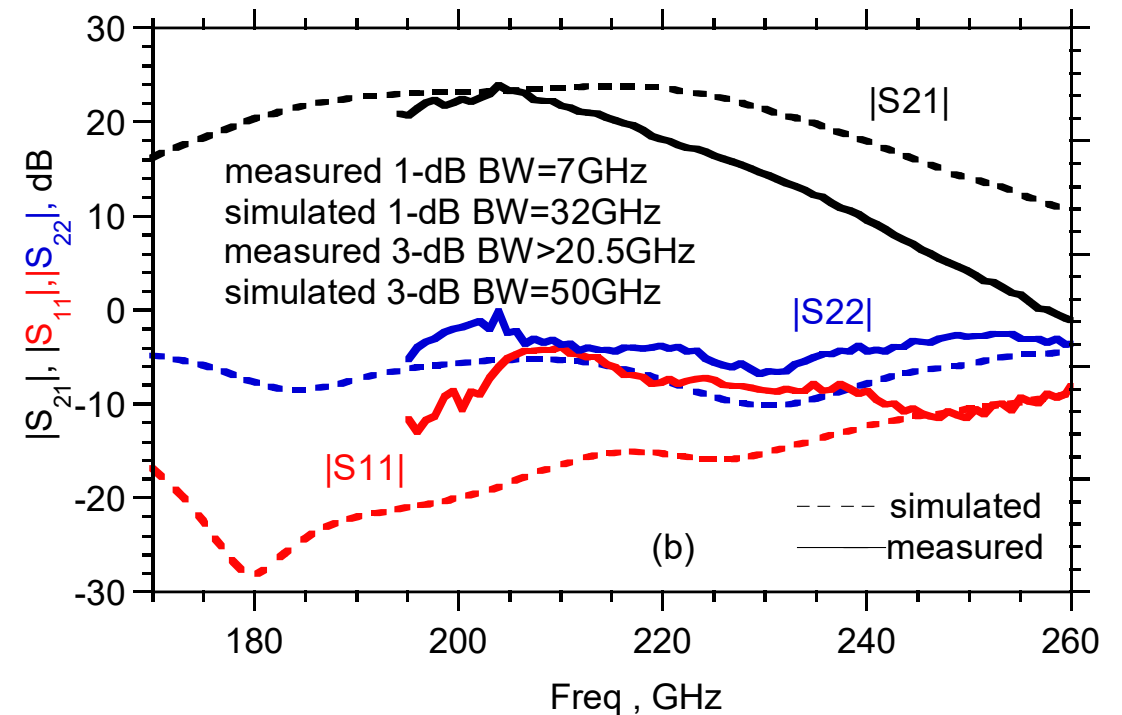


# Measurement Results: s-parameters

- Good agreement at low bias
- Some deviations are observed at higher bias-> maybe heating effect.



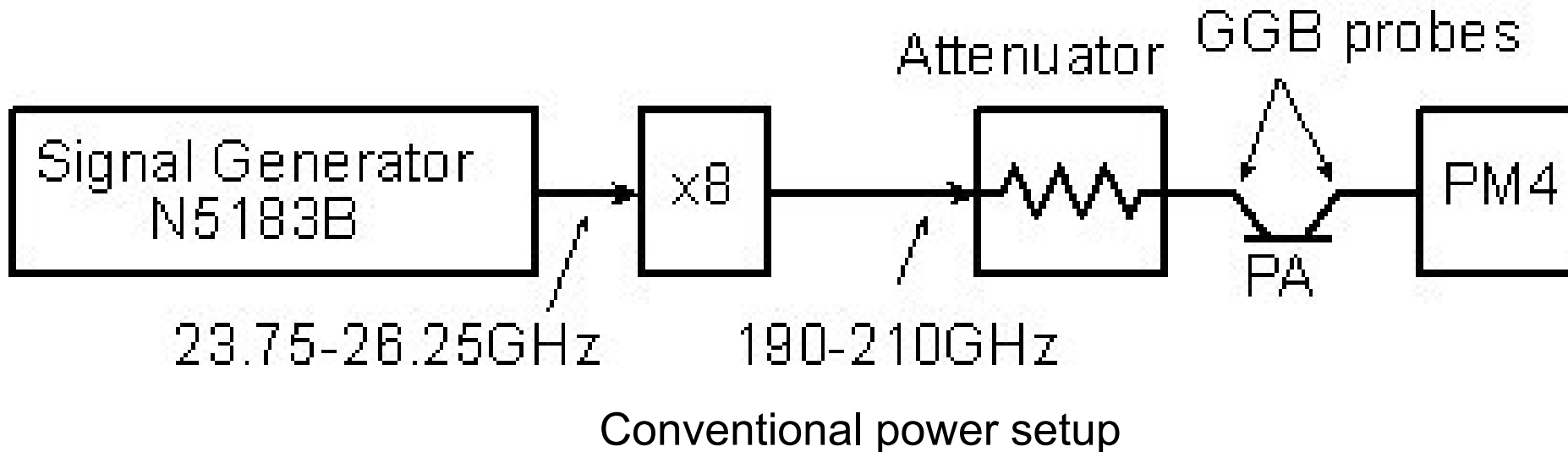
S-parameters at  $P_{DC} = 444\text{mW}$



S-parameters at  $P_{DC} = 858\text{mW}$

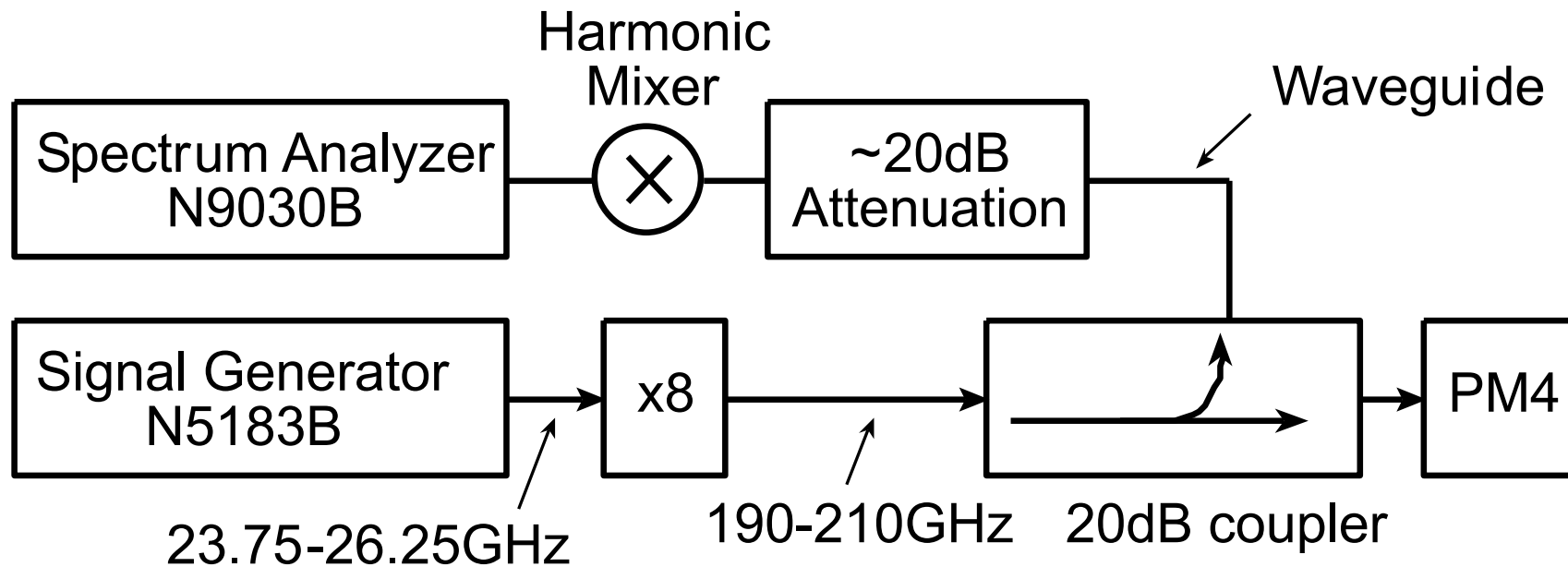
# Power Measurement: literature

- Conventional measurement: attenuator after a frequency multiplier chain.
- Power sweep: change the attenuator settings.
- Cons
  - The actual input power is unknown-> less accurate results.
  - In many cases, the attenuator is manually changed -> lift the probes and turn off the PA, not convenient.



# Proposed Approach: setup

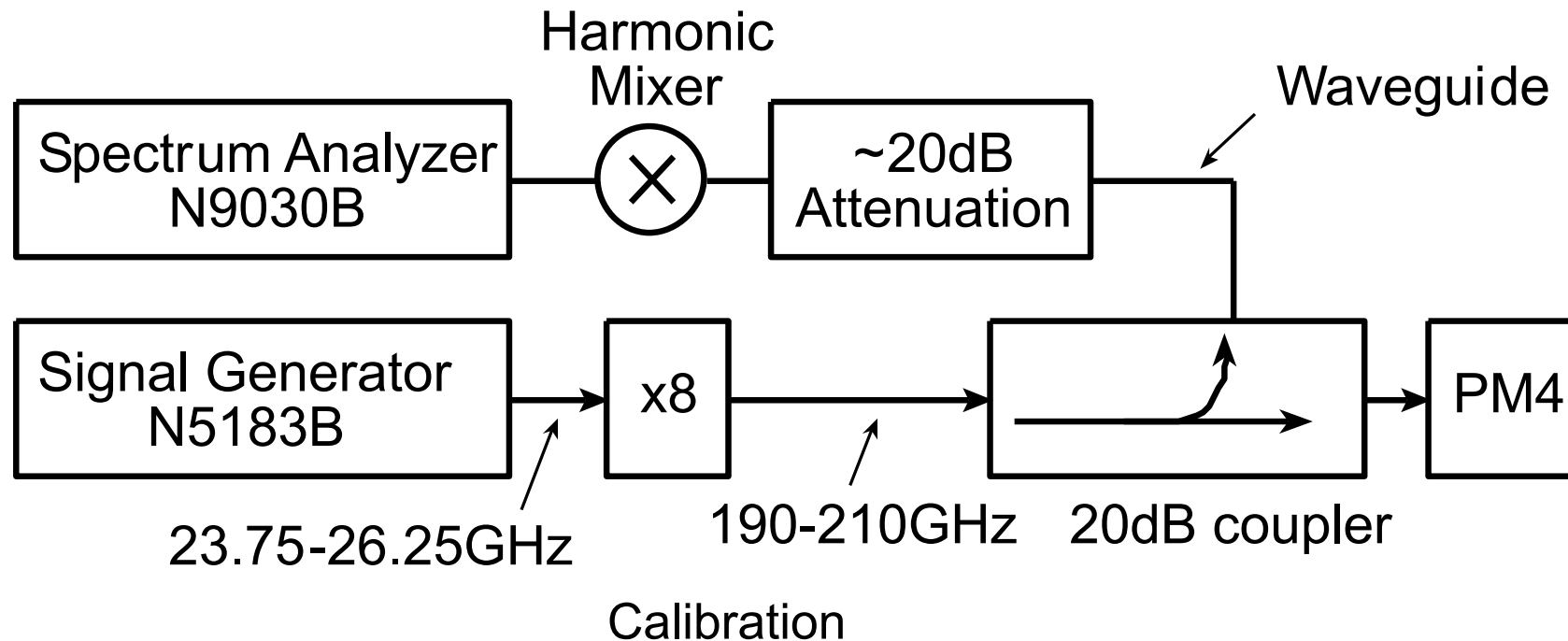
- The VDI's output power is sampled by a coupler and monitored by the spectrum analyzer.
- The spectrum analyzer readings represents the power by adding the appropriate correction factor in the calibration phase.
- Sweep input power: control the signal generator.



Proposed power setup

# Calibration phase

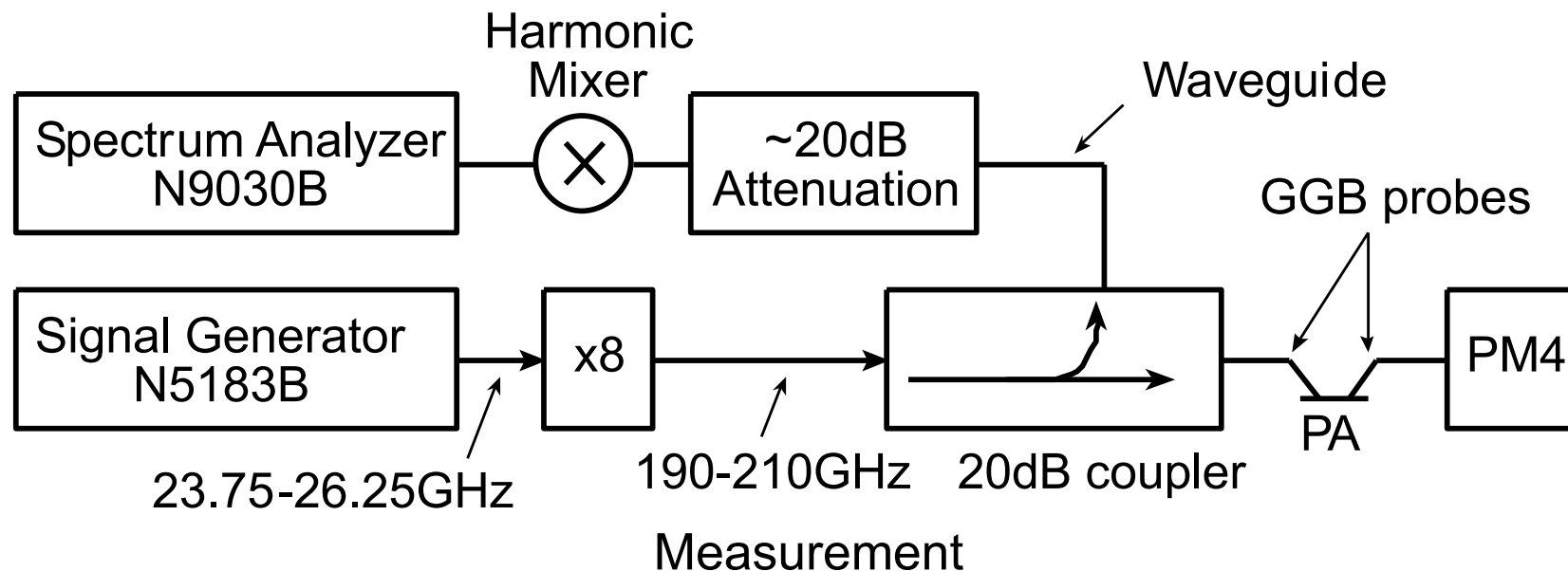
- Record the power difference (dB) between the power meter and spectrum analyzer readings.
- This difference is the correction factor that should be added to the spectrum analyzer readings to represents the actual input power.





# Measurement Phase

- Sweep the signal generator power.
- Record the spectrum analyzer readings + the appropriate correction factors. This represents the amplifier input power after calibrating the probe losses by through measurements.
- Report the power meter reading.
- The power meter readings represent the amplifier output power after calibrating probe loss.





# Pros of this measurement approach

- Accurate gain measurement even at very low input power.
- Power is swept by the signal generator  
-> Extremely convenient since all the measurements are done without lifting the probes or turn off the PA bias.

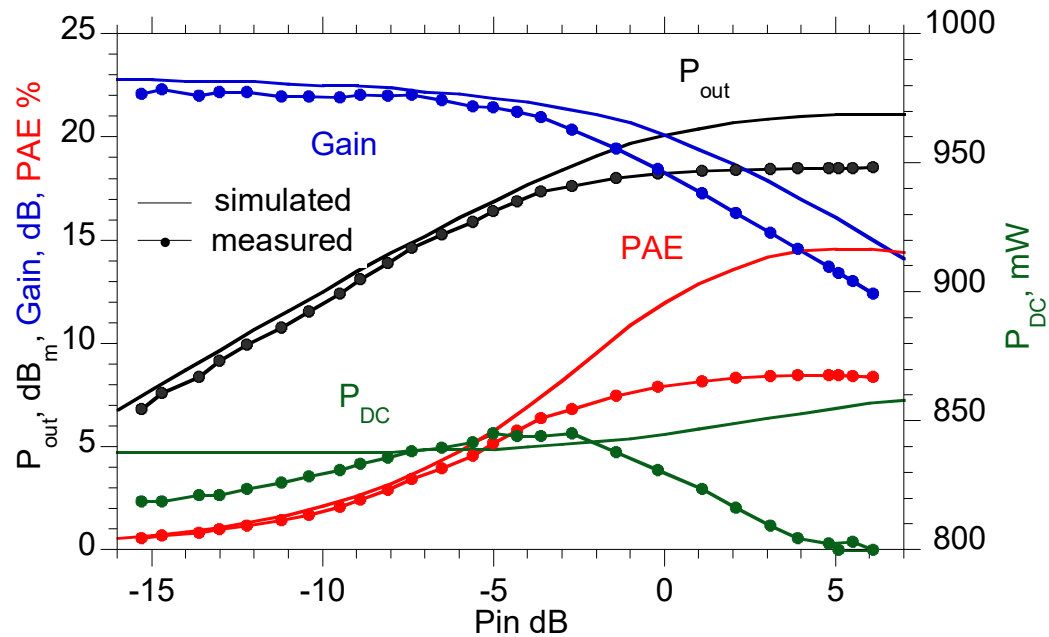


# Power Measurement Results

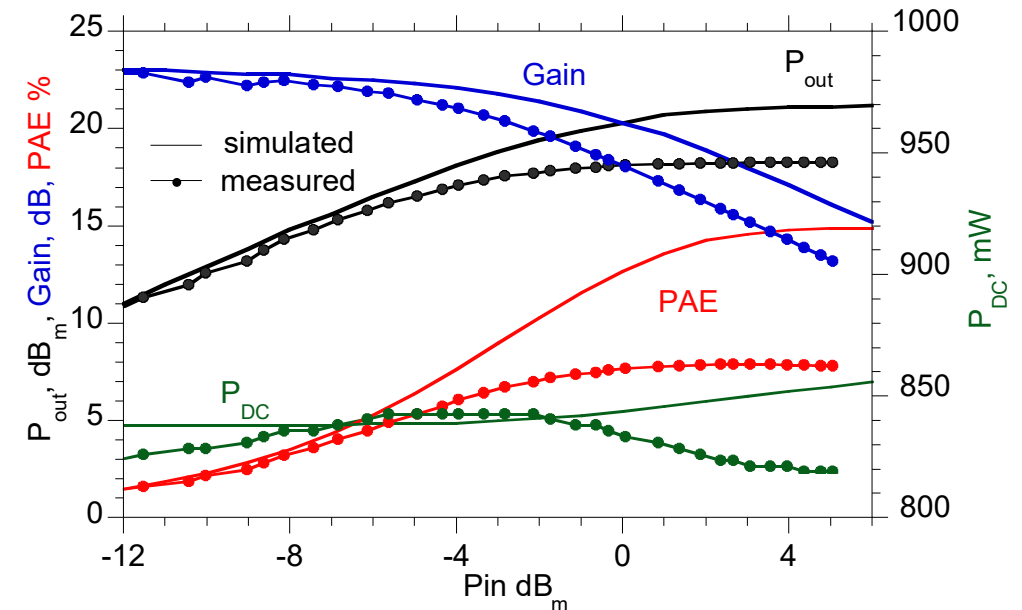
- Many points are recorded at different frequencies.

Freq, GHz	OP <sub>1dB</sub> , dBm	PAE, % at OP <sub>1dB</sub>	P <sub>sat</sub> , dBm	PAE, % at P <sub>sat</sub>
194	17.4	6.4	18.5	8.5
202	16.6	5.3	18.3	7.9

- Discrepancy between simulations and measurement maybe due to the probe conditions.



Pout, Gain, and PAE vs Pin at 194GHz

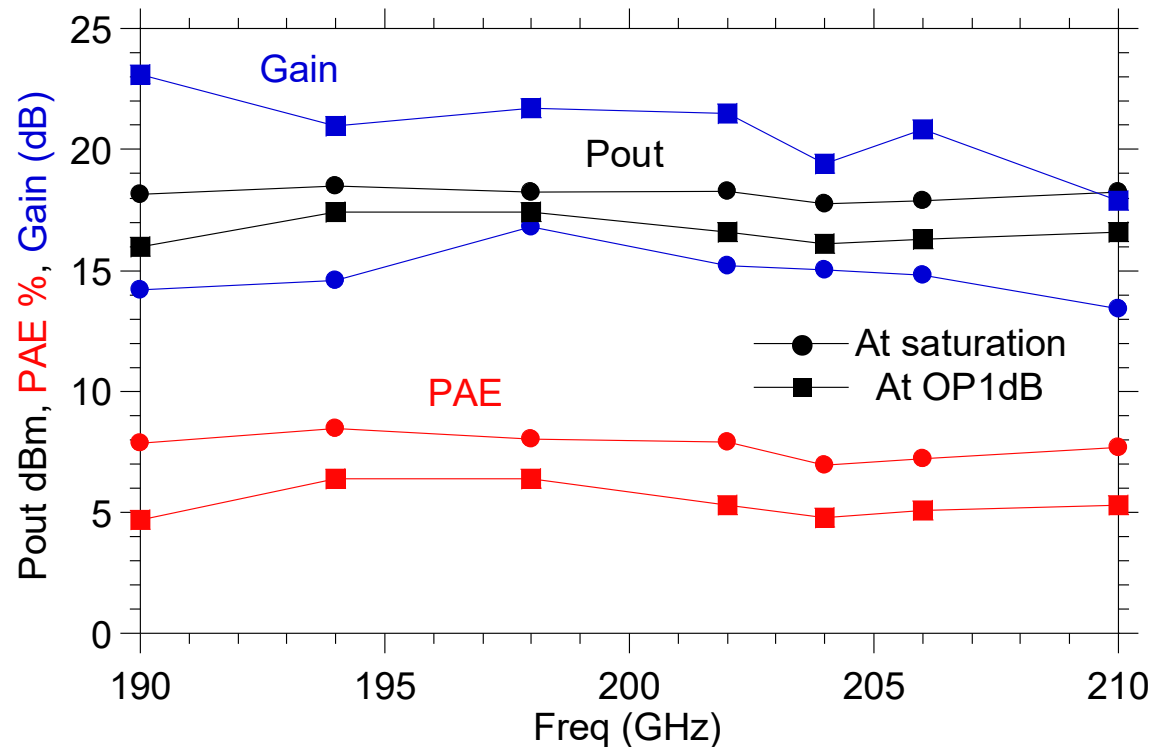


Pout, Gain, and PAE vs Pin at 202GHz



# Power Measurement Results

- More points are taken at different frequencies.
- $P_{\text{sat}}=17.7\text{-}18.5\text{dB}_m$ , with  $\text{PAE}=6.9\text{-}8.5\%$  over 190-210GHz
- $\text{OP}_{1\text{dB}}=16\text{-}17.4\text{dB}_m$  with  $\text{PAE}=4.7\text{-}6.4\%$  over 125-150GHz



Measured  $P_{\text{out}}$  with the associated PAE and gain vs. frequency reported at the peak PAE.



# State-of-the-art results

Ref	[7]	[8]	[9]	[10]	This work
Freq, GHz	204	190	180-260	190.8-244	190-210
$P_{sat}$ , dBm	18.0	11	17.5-21.5	16.2-18.9 <sup>a</sup>	17.7-18.5
Gain at $P_{sat}$ (dB)	16.5	19.2	13-17.5	19-22 <sup>a</sup>	13.4-16.8
PAE at $P_{sat}$ %	4.8	9.6	5.1	3.3-6.1	6.9-8.5%
$OP_{1dB}$ , dBm	15.5 <sup>a</sup>	3	17.5	16.1-17.16 <sup>a</sup>	16-17.4
PAE at $OP_{1dB}$ %	3.2 <sup>a</sup>	2	2.1 <sup>a</sup>	2.3-3.0 <sup>a</sup>	4.7-6.4
Gain at $OP_{1dB}$	15.5 <sup>a</sup>	27 <sup>a</sup>	23.5 <sup>a</sup>	23.8-35.0 <sup>a</sup>	17.9-23.1
$BW_{3dB}$ , GHz	>25	26	18 <sup>a</sup>	53	>20.5
Size (mm <sup>2</sup> )	0.91	0.45	1.8	1.54	1.14
$P_{DC}$ (mW)	1180	970	2620	1270	814
$P_{sat}$ /Area mW/mm <sup>2</sup>	69.2	28.2	77.9	50.6	62.1
$OP_{1dB}$ /Area mW/mm <sup>2</sup>	39	28	31.2	33.8	48.2
Technology	130nm InP	250-nm InP HBT			

- This work shows a record PAE at  $OP_{1dB}$



# Summary

- Demonstration of record PAE at G-band
- Communication transmitter requires careful attention to the performance at  $OP_{1dB}$
- Key features for highest efficiency at  $OP_{1dB}$ 
  - Proper cell topology: Capacitively linearized common base
  - Higher  $OP_{1dB}$ , and PAE
  - Driver scaling sustains good PAE
- Compact and low loss transmission line network



# Acknowledgement

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- The authors thank Teledyne Scientific & Imaging for the IC fabrication.



# Thank You



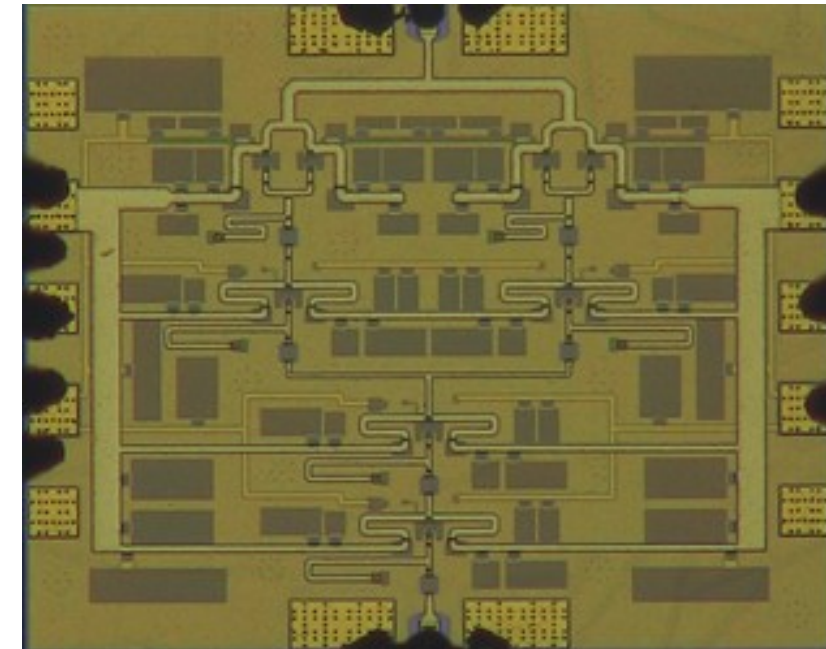
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# DC Bias Lines and Power Supply Oscillations

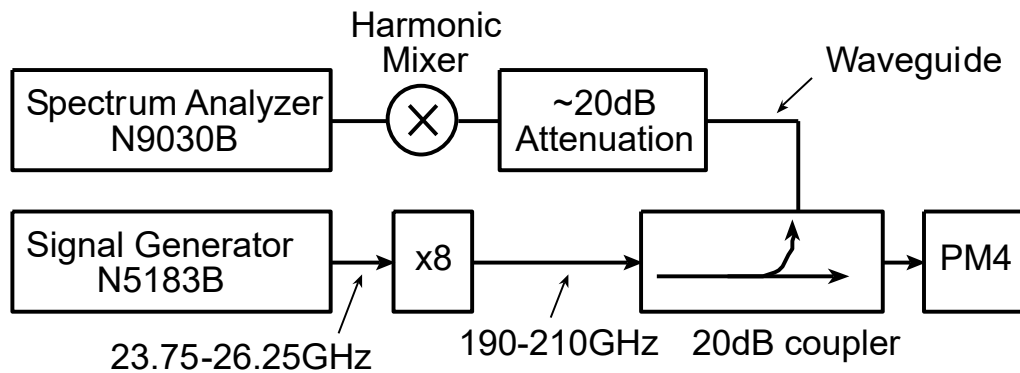
- Only two independent DC supplies -> reduce the bias complexity.
- one supply biases all stages' collectors and the second biases the stages' bases.
- There are many feedback loops-> potential stability problems.
- We noticed a potential oscillation problem at low frequencies (~GHz and lower) in **earlier designs**.
- The low frequency oscillations are not adequately modeled and does not show up in simulations.
- In this design, we added **many bypass capacitors with series resistors** to avoid out of band oscillations.
- There is no indication for oscillations.



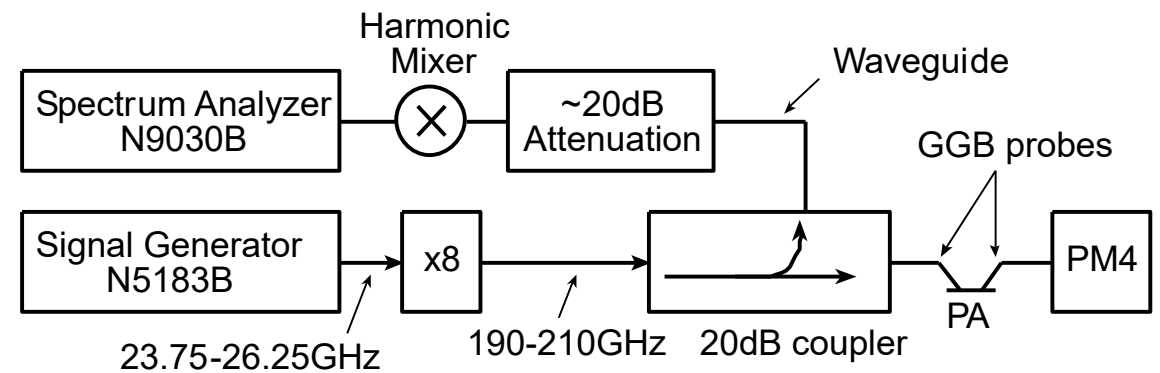


# Measurement accuracy

- The dynamic range of the power sweep is defined as follows:
  - The minimum input power: limited by the spectrum analyzer noise level.
  - Spectrum analyzer with reasonable noise levels shows smooth gain curves at low input power-> get accurate results to accurately report  $OP_{1dB}$ .
  - The maximum power: limited by the harmonic mixer saturation limit.



Calibration



Measurement



# Measurement accuracy

- Probe losses are calibrated by through measurement.
- Old probes show non-50 $\Omega$  impedance which degrades the output power.
- So, the probes may contribute to higher losses than the one measured in the through measurement.
- We did the measurement with an old probe pair, and we believe that the results could be improved by a newer one.